

**Features**

- $V_{ds} = 40V$  ,  $I_d = 255A$   
 $R_{DS(ON)}=1.2m\Omega$  (typ.) @  $V_{GS}=10V$   
 $R_{DS(ON)}=1.9m\Omega$  (typ.) @  $V_{GS}=4.5V$
- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- Wettable Flanks

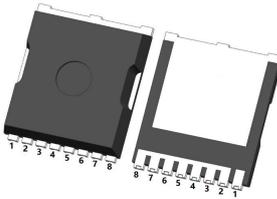
**Application**

- BLDC Motor driver
- SMPS 2nd Synchronous Rectifier
- DC-DC Converter

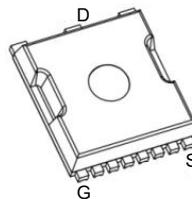


**Package**

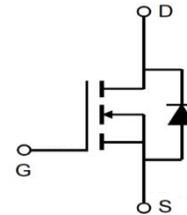
Top View



Top View



Schematic diagram



**Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
TF015N04TG	TF015N04TG	TOLL-8	-	-	-

**Absolute Maximum Ratings** ( $T_c=25^\circ C$  unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	$T_c=25^\circ C$	255
		$T_c=100^\circ C$	178
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	640	A
Single Pulse Avalanche Energy <sup>2</sup>	EAS	430	mJ
Total Power Dissipation	$P_D$	180	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	$R_{\theta JA}$	39	$^\circ C/W$
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	1.3	$^\circ C/W$



**Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	40	-	-	V
Gate-body Leakage current	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$T_J=25^\circ\text{C}$	$I_{DSS}$ $V_{DS} = 36V, V_{GS} = 0V$	-	-	1	$\mu A$
	$T_J=100^\circ\text{C}$		-	-	100	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	1.5	2.5	V
Drain-Source on-Resistance <sup>4</sup>	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 30A$	-	1.20	1.8	m $\Omega$
		$V_{GS} = 4.5V, I_D = 20A$	-	1.90	2.8	
<b>Dynamic Characteristics<sup>5</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 20V, V_{GS} = 0V,$ $f = 1\text{MHz}$	-	4217	-	pF
Output Capacitance	$C_{oss}$		-	898	-	
Reverse Transfer Capacitance	$C_{rss}$		-	838	-	
Gate Resistance	$R_g$	$f = 1\text{MHz}$	-	1.0	-	$\Omega$
<b>Switching Characteristics<sup>5</sup></b>						
Total Gate Charge	$Q_g$	$V_{GS} = 10V, V_{DS} = 20V,$ $I_D = 30A$	-	96.8	-	nC
Gate-Source Charge	$Q_{gs}$		-	17.8	-	
Gate-Drain Charge	$Q_{gd}$		-	15.8	-	
Turn-on Delay Time	$t_{d(on)}$	$V_{GS} = 10V, V_{DD} = 20V,$ $R_G = 3\Omega, I_D = 30A$	-	23.0	-	ns
Rise Time	$t_r$		-	8.9	-	
Turn-off Delay Time	$t_{d(off)}$		-	73.5	-	
Fall Time	$t_f$		-	17.8	-	
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 30A, di/dt = 100A/\mu s$	-	58.0	-	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	77.0	-	nC
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{SD}$	$I_S = 30A, V_{GS} = 0V$	-	-	1.2	V
Continuous Source Current	$T_C=25^\circ\text{C}$	$I_S$	-	-	160	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)} = 150^\circ\text{C}$ .
2. The EAS data shows Max. rating . The test condition is  $V_{DD} = 20V, V_{GS} = 10V, L = 0.5\text{mH}, I_{AS} = 20A$ .
3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
5. This value is guaranteed by design hence it is not included in the production test.

**Typical Characteristics**

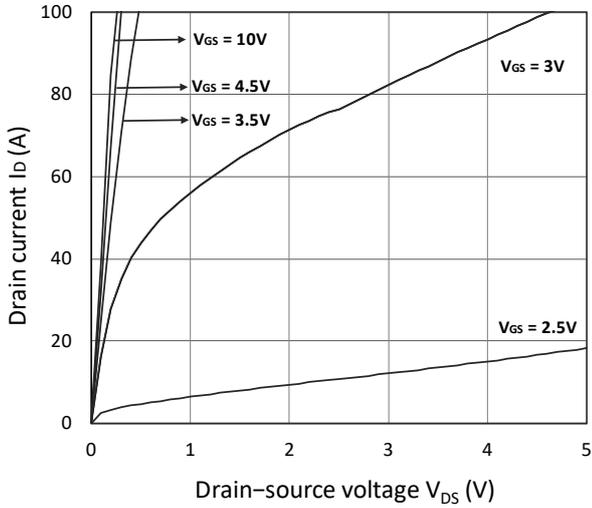


Figure 1. Output Characteristics

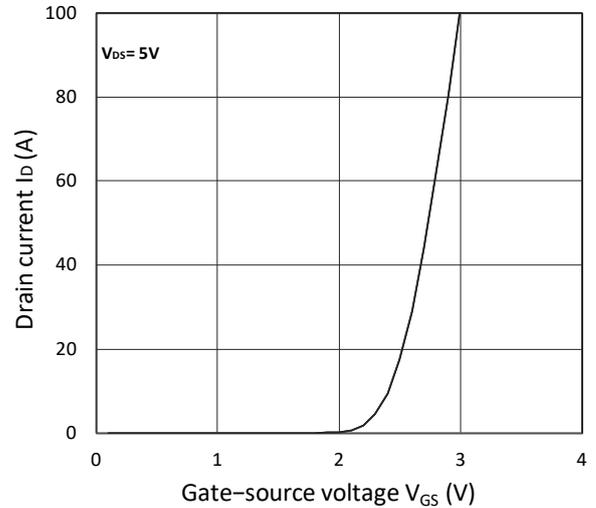


Figure 2. Transfer Characteristics

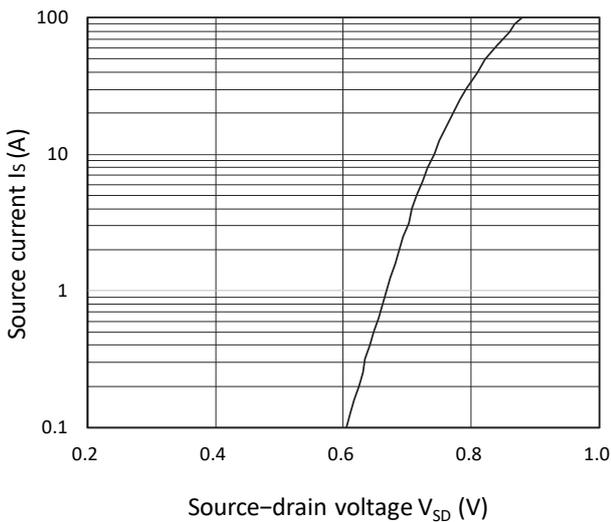


Figure 3. Forward Characteristics of Reverse

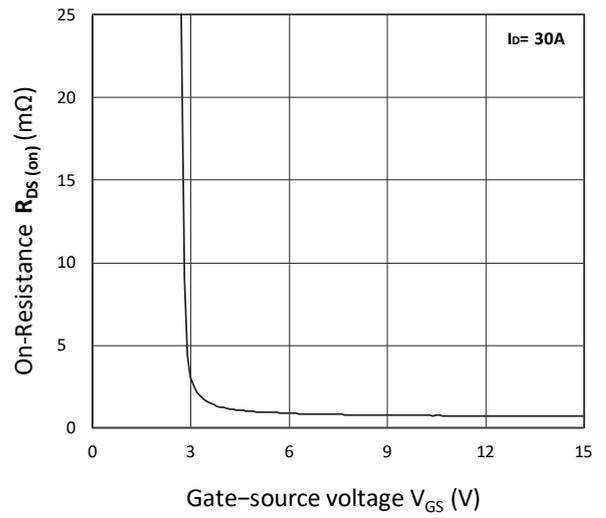


Figure 4.  $R_{DS(ON)}$  vs.  $V_{GS}$

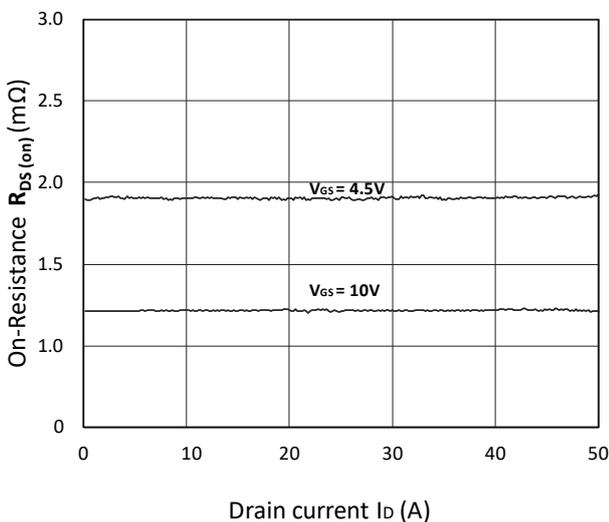


Figure 5.  $R_{DS(ON)}$  vs.  $I_D$

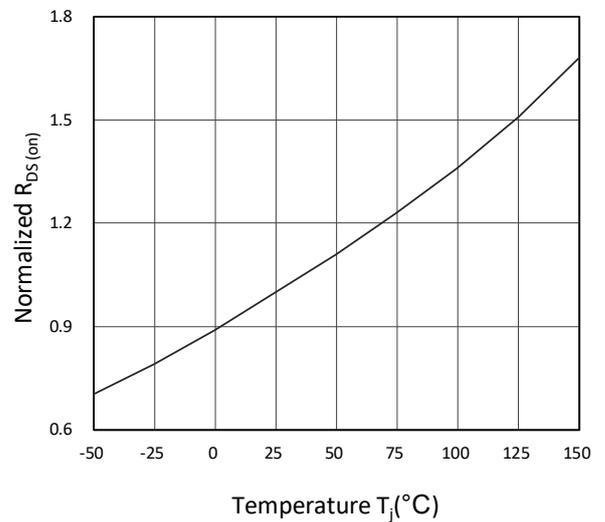


Figure 6. Normalized  $R_{DS(ON)}$  vs. Temperature

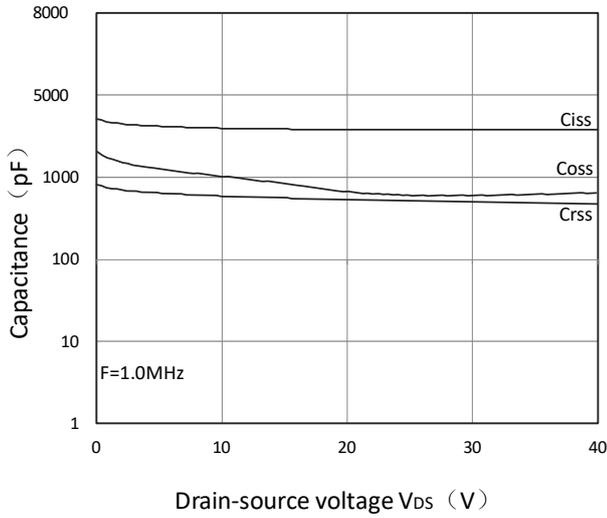


Figure 7. Capacitance Characteristics

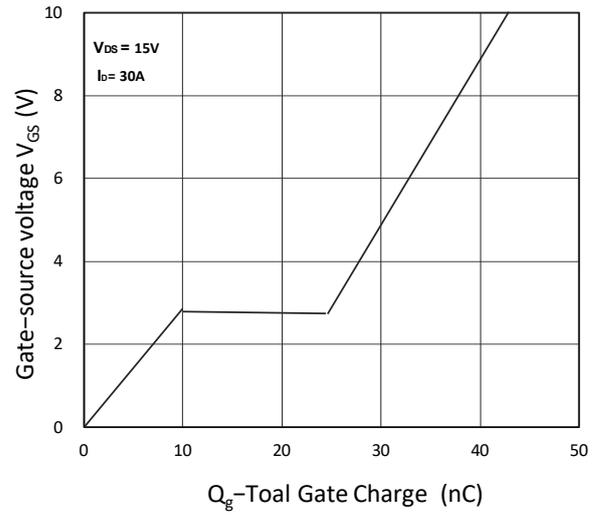


Figure 8. Gate Charge Characteristics

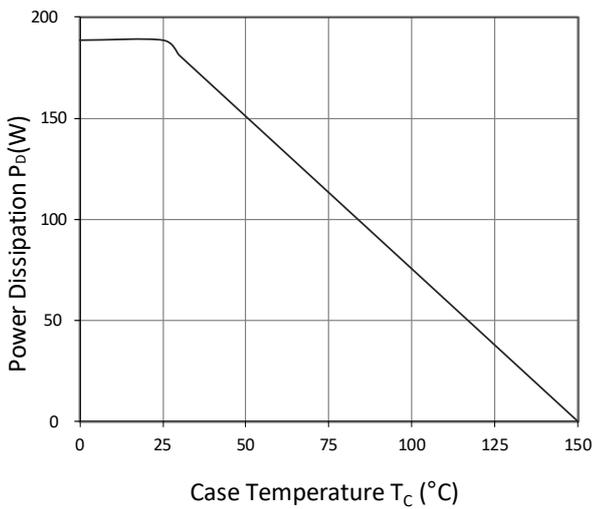


Figure 9. Power Dissipation

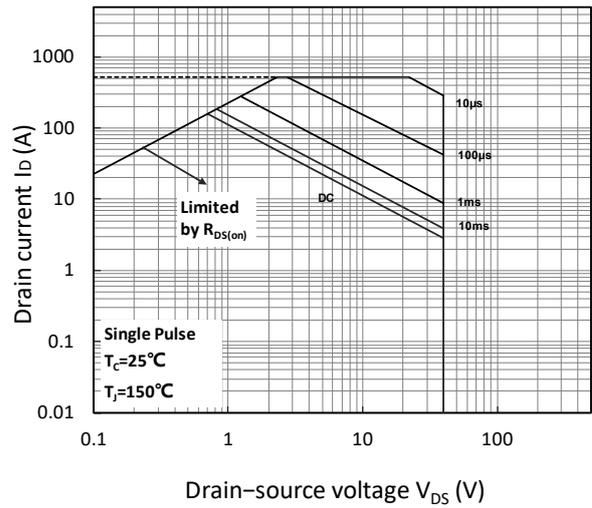


Figure 10. Safe Operating Area

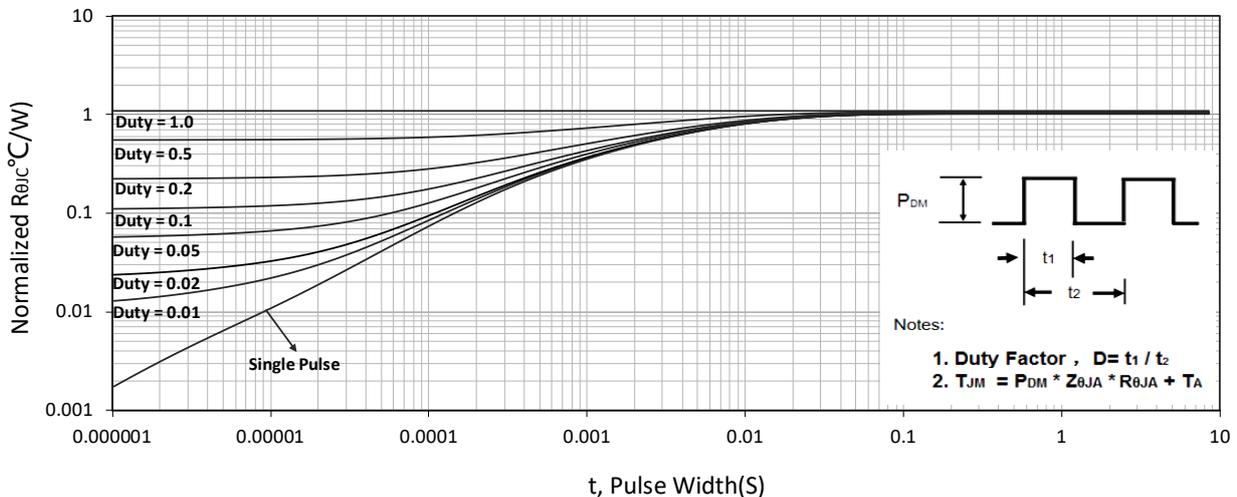
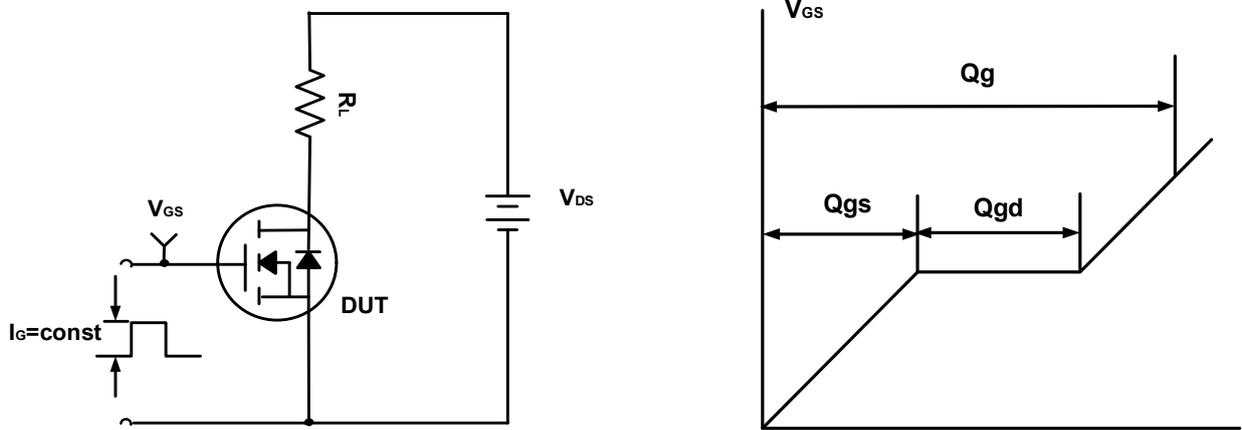
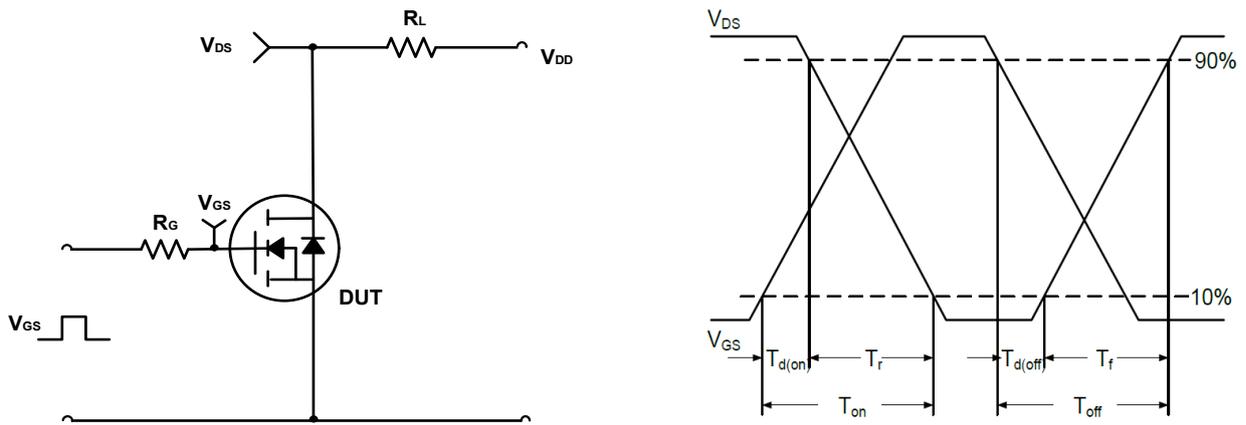


Figure 11. Normalized Maximum Transient Thermal Impedance

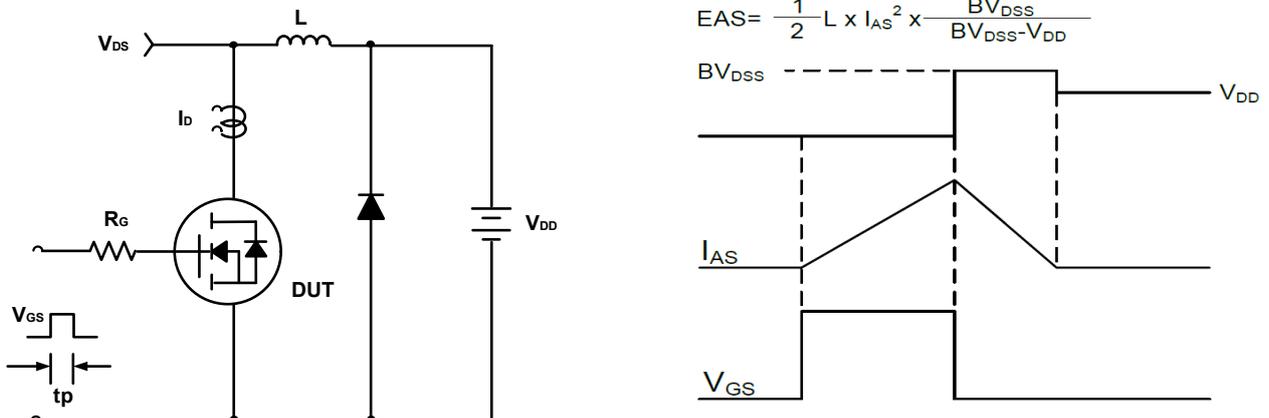
**Test Circuit**



**Figure A. Gate Charge Test Circuit & Waveforms**

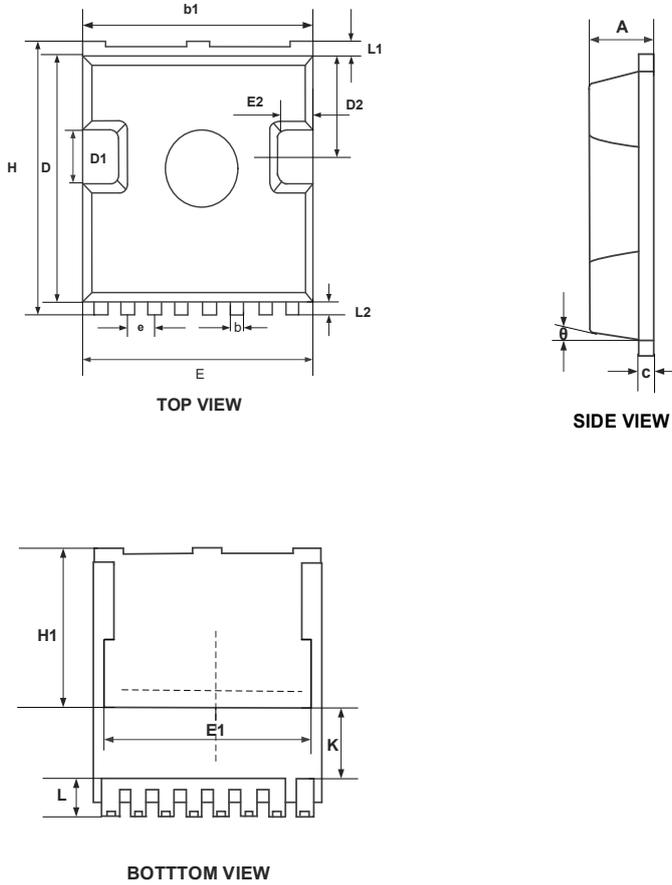


**Figure B. Switching Test Circuit & Waveforms**



**Figure C. Unclamped Inductive Switching Circuit & Waveforms**

**Mechanical Dimensions for TOLL**



**COMMON DIMENSIONS**

SYMBOL	MM	
	MIN	MAX
A	2.20	2.40
b	0.60	0.90
$b_1$	9.70	9.90
c	0.40	0.60
D	10.20	10.60
$D_1$	3.10	3.50
$D_2$	4.45	4.75
E	9.70	10.10
$E_1$	7.80BSC	
$E_2$	0.50	0.70
e	1.200 BSC	
H	11.45	11.90
$H_1$	6.75 BSC	
K	3.10 REF	
L	1.70	2.10
$L_1$	0.60	0.80
$L_2$	0.50	0.70
$\theta$	10° REF	